

Commissioner for Patents  
May 14, 2007  
Page 2 of 8

Serial No. 10/782,455  
Art Unit: 2831 Examiner: Angel R Estrada  
IBM Docket: AUS920031049US1(4037)

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AMENDMENT OF THE CLAIMS

1-33 (Cancelled)

34. (Currently Amended) The enclosure of claim 3[[3]]5, further comprising other components coupled with the pattern of interconnects via the mounting sites.

35. (Currently Amended) ~~The enclosure of claim 34,~~ An enclosure for an electronic device, the enclosure comprising:

an interior surface and an outside surface of the enclosure, the interior surface enclosing the electronic device;

mounting sites to mount integrated circuits, wherein the mounting sites couple with the interior surface;

a pattern of interconnects coupled with the interior surface and interconnected with the mounting sites to transmit signals between the integrated circuits; and  
at least one switch coupled with the pattern of interconnects at the interior surface and exposed via the outside surface of the enclosure to receive input from outside of the enclosure, wherein the at least one switch comprises an optical switch to toggle in response to a change in light sensed by the optical switch.

36. (Currently Amended) ~~The enclosure of claim 34,~~ An enclosure for an electronic device, the enclosure comprising:

an interior surface and an outside surface of the enclosure, the interior surface enclosing the electronic device;

mounting sites to mount integrated circuits, wherein the mounting sites couple with the interior surface;

a pattern of interconnects coupled with the interior surface and interconnected with the mounting sites to transmit signals between the integrated circuits; and

Commissioner for Patents  
May 14, 2007  
Page 3 of 8

Serial No. 10/782,455  
Art Unit: 2831 Examiner: Angel R Estrada  
IBM Docket: AUS920031049US1(4037)

at least one switch coupled with the pattern of interconnects at the interior surface and exposed via the outside surface of the enclosure to receive input from outside of the enclosure, wherein the at least one switch comprises a pressure-sensitive switch coupled with the pattern of interconnects via one of the mounts.

37. (Currently Amended) The enclosure of claim 3[[3]]5, wherein the pattern of interconnects comprises a conductive paint applied directly to the enclosure, wherein the enclosure is composed of a substantially non-conductive plastic.
38. (Previously Presented) The enclosure of claim 37, wherein the enclosure is composed of a pliable material.
39. (Currently Amended) The enclosure of claim 3[3]5, wherein the pattern of interconnects is coupled with the enclosure via at least one layer of non-conductive laminates.
40. (Currently Amended) The enclosure of claim 3[3]5, wherein the pattern of interconnects applied to an interior surface of the enclosure comprises a layer of metal having portions etched away to reveal the pattern of interconnects.
41. (Currently Amended) A system comprising:  
an enclosure comprising an interior surface and an outside surface, the interior surface enclosing an electronic device;  
integrated circuits;  
mounts in the enclosure to mount the integrated circuits, wherein the mounts couple with the interior surface;  
a pattern of interconnects coupled with the interior surface and interconnected with the mounts to transmit signals between the integrated circuits; and  
at least one switch coupled with the pattern of interconnects and exposed via the outside surface of the enclosure to receive input from outside of the system; and

Commissioner for Patents  
May 14, 2007  
Page 1 of 9

Serial No. 10/782,455  
Art Unit: 2831 Examiner: Angel R Estrada  
IBM Docket: AUS920031049US1(4037)

sensors to sense environmental conditions, the sensors being oriented to face the exterior of the enclosure.

42. (Cancelled)

43. (Previously Presented) The system of claim 41, wherein the pattern of interconnects resides on a laminate; the laminate being adhered to the interior surface of the enclosure.

44. (Previously Presented) The system of claim 41, wherein the pattern of interconnects is coupled with a circuit board internal of the enclosure to communicatively couple the integrated circuits with other components mounted to the circuit board.

45-60 (Cancelled)

61. (New) The enclosure of claim 36, further comprising other components coupled with the pattern of interconnects via the mounting sites.

62. (New) The enclosure of claim 36, wherein the at least one switch further comprises an optical switch to toggle in response to a change in light sensed by the optical switch.

63. (New) The enclosure of claim 36, wherein the pattern of interconnects comprises a conductive paint applied directly to the enclosure, wherein the enclosure is composed of a substantially non-conductive plastic.

64. (New) The enclosure of claim 36, wherein the enclosure is composed of a pliable material.

65. (New) The enclosure of claim 36, wherein the pattern of interconnects is coupled with the enclosure via at least one layer of non-conductive laminates.

*Commissioner for Patents*  
*May 14, 2007*  
*Page 5 of 8*

*Serial No. 10/782,455*  
*Art Unit: 2831 Examiner: Angel R Estrada*  
*IBM Docket: AUS920031049US1(4037)*

66. (New) The enclosure of claim 36, wherein the pattern of interconnects applied to an interior surface of the enclosure comprises a layer of metal having portions etched away to reveal the pattern of interconnects.